



# BYW51/F/G/FP/R-200

## HIGH EFFICIENCY FAST RECOVERY RECTIFIER DIODES

### MAIN PRODUCT CHARACTERISTICS

$I_{F(AV)}$	2 x 10 A
$V_{RRM}$	200 V
$T_j$ (max)	150 °C
$V_F$ (max)	0.85 V
$t_{rr}$ (max)	25 ns

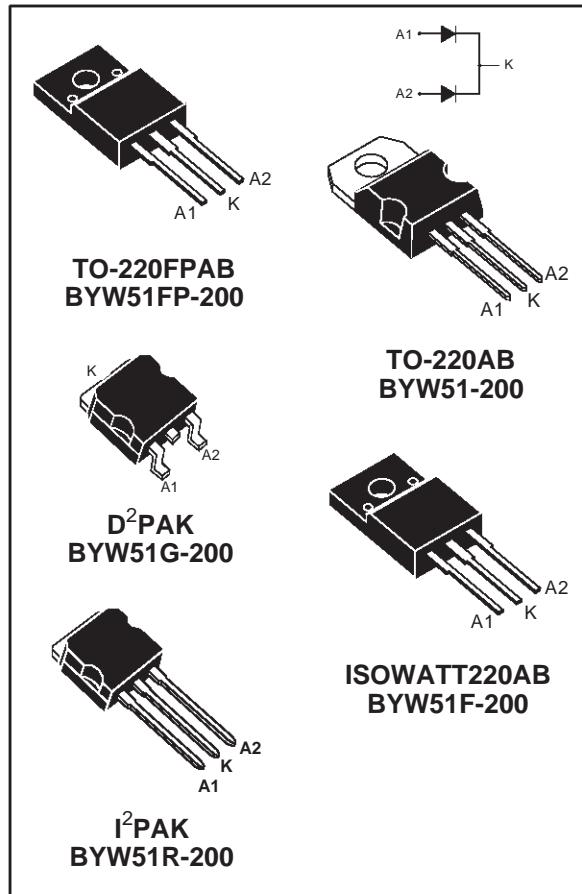
### FEATURES AND BENEFITS

- SUITED FOR SMPS
- VERY LOW FORWARD LOSSES
- NEGLIGIBLE SWITCHING LOSSES
- HIGH SURGE CURRENT CAPABILITY
- INSULATED PACKAGES (ISOWATT220AB / TO-220FP) :  
Insulation voltage = 2000 V DC  
Capacitance = 12 pF

### DESCRIPTION

Dual center tap rectifier suited for Switched Mode Power Supplies and high frequency DC to DC converters.

Packaged in TO-220AB, ISOWATT220AB, TO-220FP, D<sup>2</sup>PAK or I<sup>2</sup>PAK, this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection applications.



### ABSOLUTE RATINGS (limiting values, per diode)

Symbol	Parameter				Value	Unit		
$V_{RRM}$	Repetitive peak reverse voltage				200	V		
$I_{F(RMS)}$	RMS forward current				20	A		
$I_{F(AV)}$	Average forward current $\delta = 0.5$	TO-220AB / D <sup>2</sup> PAK	$T_c=120^\circ\text{C}$	Per diode	10	A		
		I <sup>2</sup> PAK		Per device	20			
		ISOWATT220AB	$T_c=95^\circ\text{C}$	Per diode	10			
		TO-220FPAB	$T_c=85^\circ\text{C}$	Per device	20			
				Per diode	10			
				Per device	20			
$I_{FSM}$	Surge non repetitive forward current				100	A		
$T_{stg}$	Storage temperature range				- 65 to + 150	°C		
$T_j$	Maximum operating junction temperature				150	°C		

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### THERMAL RESISTANCES

Symbol	Parameter			Value	Unit
$R_{th(j-c)}$	Junction to case	TO-220AB / D <sup>2</sup> PAK / I <sup>2</sup> PAK		Per diode	2.5
				Total	1.4
	ISOWATT220AB			Per diode	5.1
				Total	4.05
	TO-220FPAB			Per diode	5.7
				Total	4.6
$R_{th(c)}$	Coupling	TO-220AB / D <sup>2</sup> PAK / I <sup>2</sup> PAK			0.25
		ISOWATT220AB			3.0
		TO-220FPAB			3.5

When diodes 1 and 2 are used simultaneously :

$$\Delta T_c \text{ (diode 1)} = P(\text{diode 1}) \times R_{th(j-c)} \text{ (Per diode)} + P(\text{diode 2}) \times R_{th(c)}$$

### STATIC ELECTRICAL CHARACTERISTICS (Per diode)

Symbol	Parameter	Test Conditions		Min.	Typ.	Max.	Unit
$I_R$ *	Reverse leakage current	$T_j = 25^\circ\text{C}$	$V_R = V_{RRM}$			15	$\mu\text{A}$
		$T_j = 100^\circ\text{C}$				1	mA
$V_F$ **	Forward voltage drop	$T_j = 125^\circ\text{C}$	$I_F = 8 \text{ A}$			0.85	V
		$T_j = 125^\circ\text{C}$	$I_F = 16 \text{ A}$			1.05	
		$T_j = 25^\circ\text{C}$	$I_F = 16 \text{ A}$			1.15	

Pulse test : \* tp = 5 ms,  $\delta < 2\%$

\*\* tp = 380  $\mu\text{s}$ ,  $\delta < 2\%$

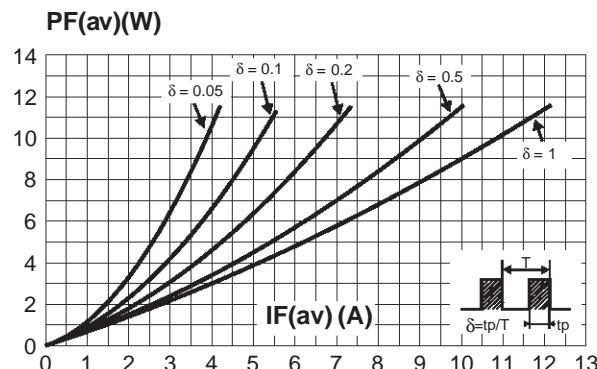
To evaluate the conduction losses use the following equation :

$$P = 0.65 \times I_{F(AV)} + 0.025 \times I_F^2(\text{RMS})$$

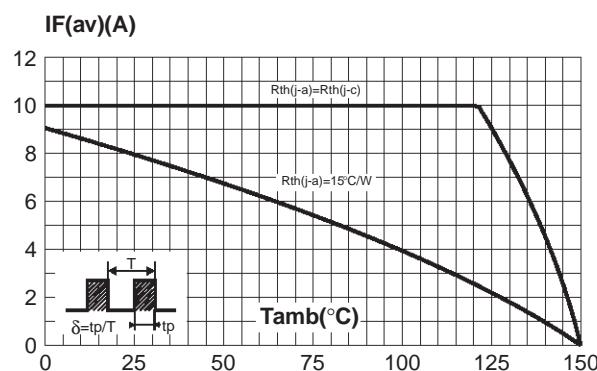
### RECOVERY CHARACTERISTICS

Symbol	Test Conditions			Typ.	Max.	Unit
trr	$T_j = 25^\circ\text{C}$	$I_F = 0.5\text{A}$	$I_{rr} = 0.25\text{A}$		25	ns
		$I_F = 1\text{A}$ $V_R = 30\text{V}$	$dI_F/dt = -50\text{A}/\mu\text{s}$		35	
tfr	$T_j = 25^\circ\text{C}$	$I_F = 1\text{A}$ $V_{FR} = 1.1 \times V_F \text{ max}$	$dI_F/dt = -50\text{A}/\mu\text{s}$	15		ns
V <sub>FP</sub>	$T_j = 25^\circ\text{C}$	$I_F = 1\text{A}$	$dI_F/dt = -50\text{A}/\mu\text{s}$	2		V

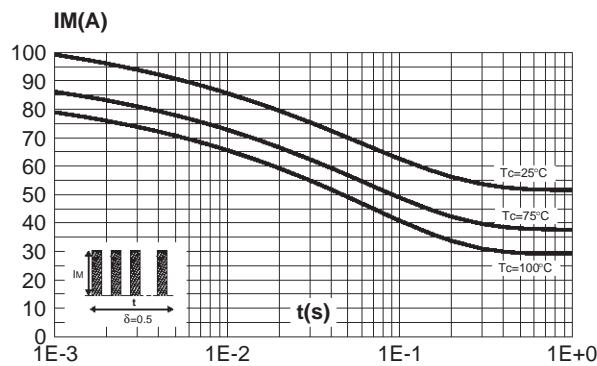
**Fig. 1:** Average forward power dissipation versus average forward current (per diode).



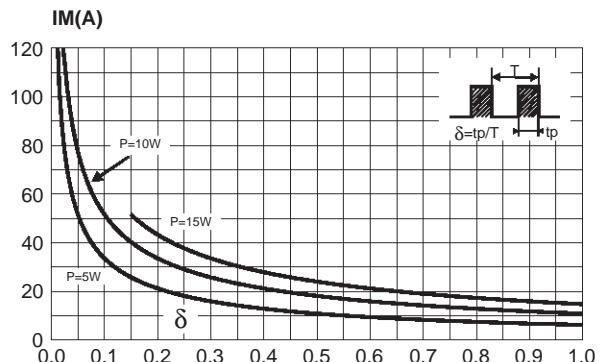
**Fig. 3-1:** Average forward current versus ambient temperature ( $\delta = 0.5$ , D<sup>2</sup>PAK, TO-220AB).



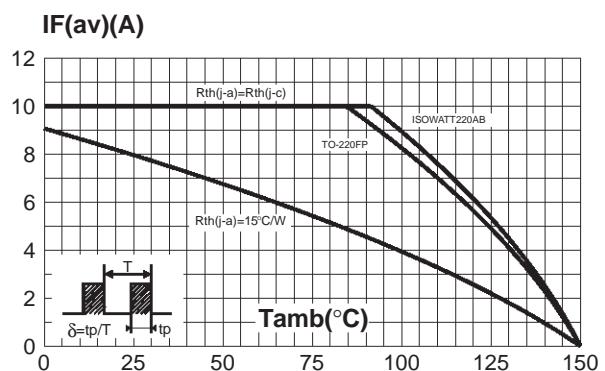
**Fig. 4-1:** Non repetitive surge peak forward current versus overload duration (D<sup>2</sup>PAK, TO-220AB)



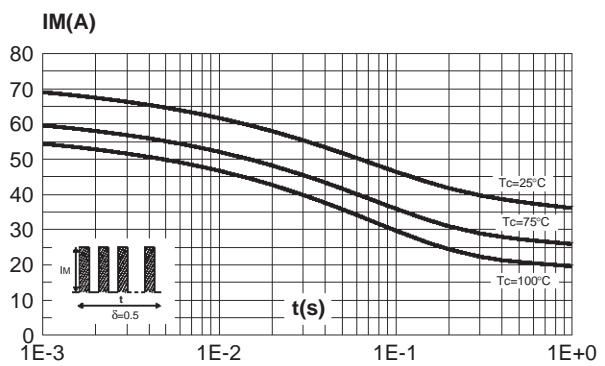
**Fig. 2:** Peak current versus form factor (per diode).



**Fig. 3-2:** Average forward current versus ambient temperature ( $\delta = 0.5$ , ISOWATT220AB, TO-220FPAB).

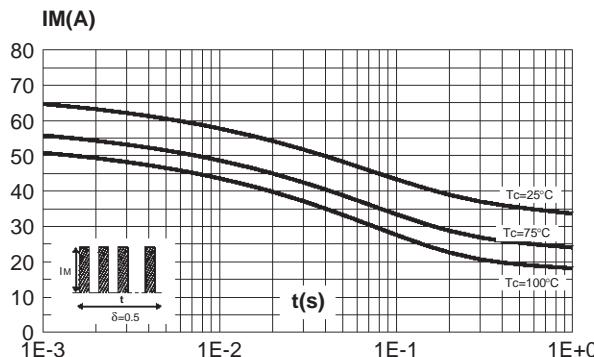


**Fig. 4-2:** Non repetitive surge peak forward current versus overload duration (ISOWATT220AB).

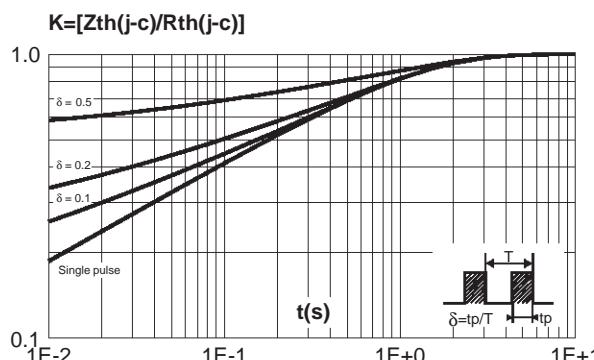


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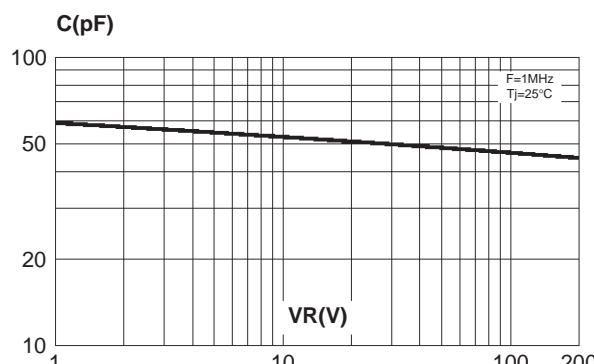
**Fig. 4-3:** Non repetitive surge peak forward current versus overload duration (TO-220FPAB).



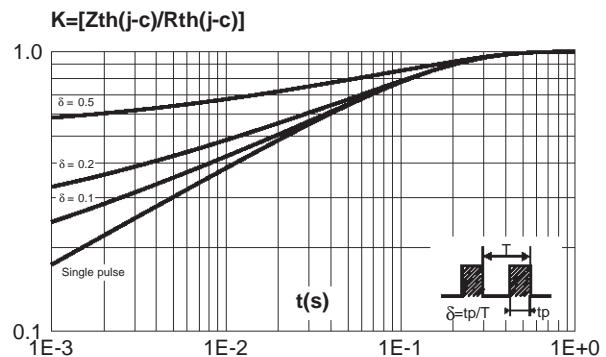
**Fig. 5-2:** Relative variation of thermal impedance junction to case versus pulse duration (ISOWATT220AB, TO-220FPAB).



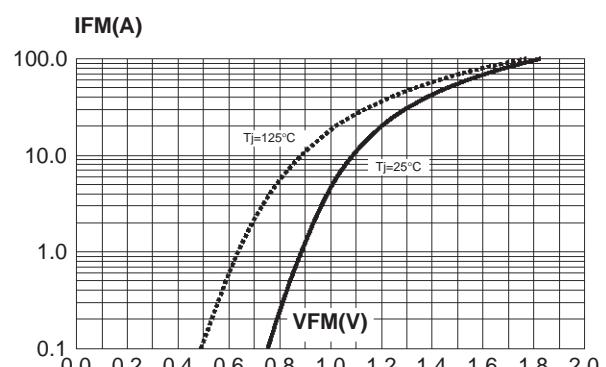
**Fig. 7:** Junction capacitance versus reverse voltage applied (typical values, per diode).



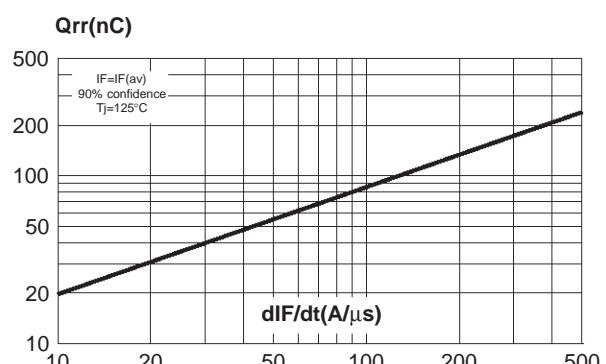
**Fig. 5-1:** Relative variation of thermal impedance junction to case versus pulse duration (D<sup>2</sup>PAK, TO-220AB).



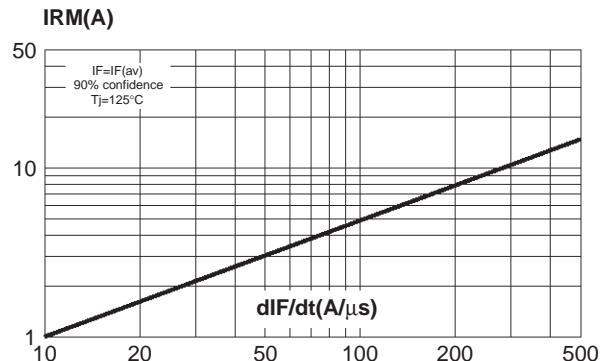
**Fig. 6:** Forward voltage drop versus forward current (maximum values, per diode).



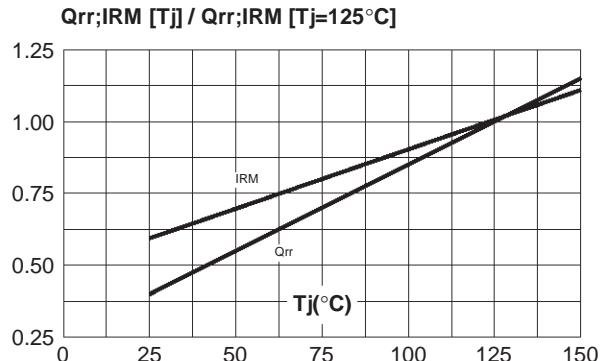
**Fig. 8:** Reverse recovery charges versus  $dI_F/dt$  (per diode).



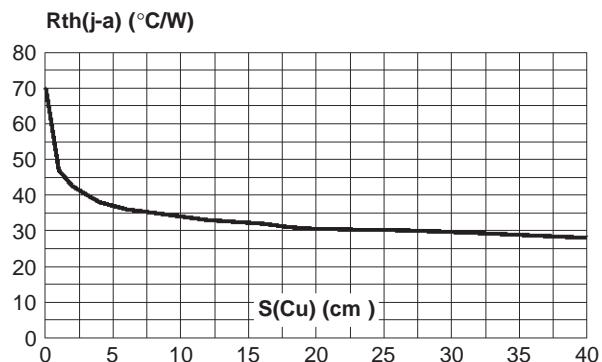
**Fig. 9:** Peak reverse recovery current versus  $dI_F/dt$  (per diode).



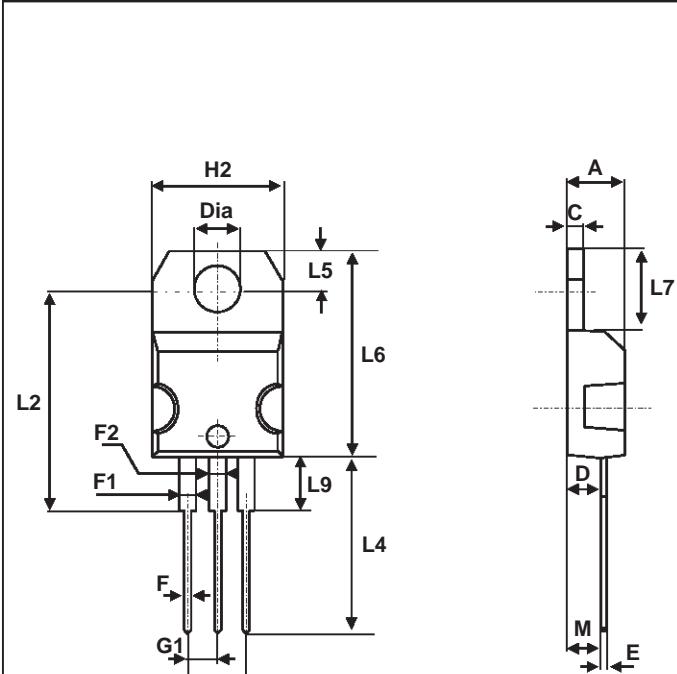
**Fig. 10:** Dynamic parameters versus junction temperature.



**Fig. 11:** Thermal resistance junction to ambient versus copper surface under tab (Epoxy printed circuit board FR4, copper thickness: 35 $\mu m$ ) (D<sup>2</sup>PAK).

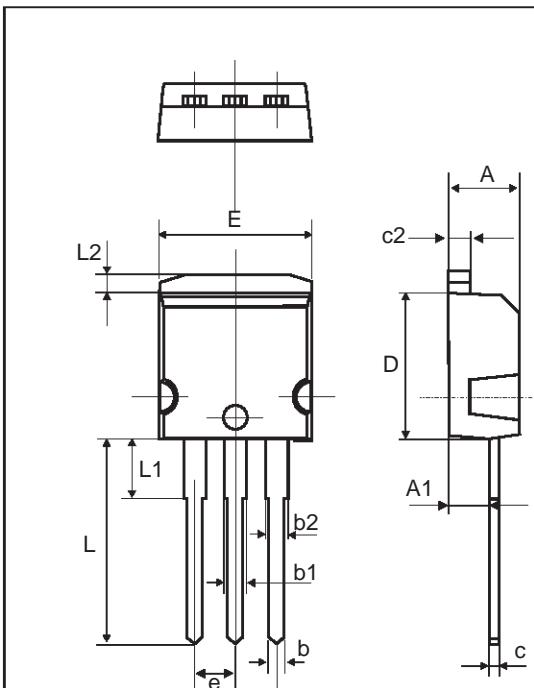


**PACKAGE MECHANICAL DATA**  
TO-220AB (JEDEC compatible)



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
F2	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
G1	2.40	2.70	0.094	0.106
H2	10	10.40	0.393	0.409
L2	16.4 typ.		0.645 typ.	
L4	13	14	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam.	3.75	3.85	0.147	0.151

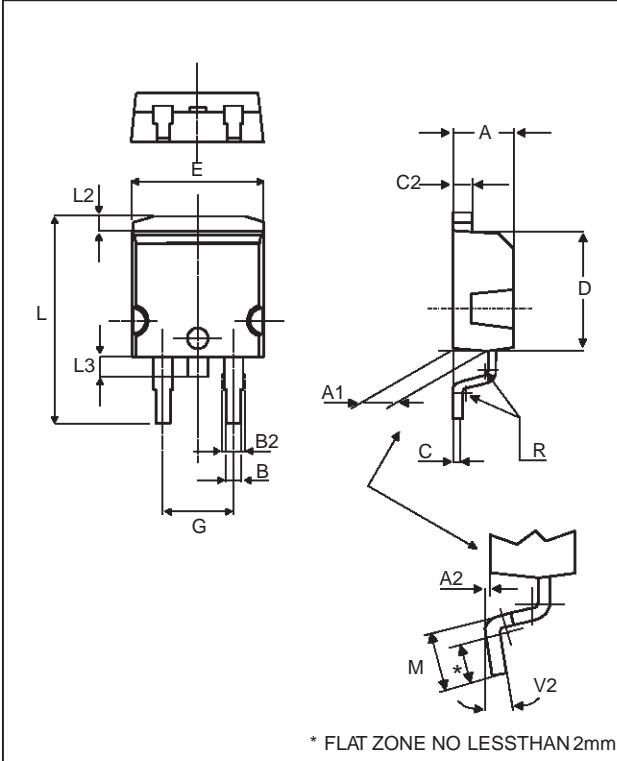
**PACKAGE MECHANICAL DATA**  
I<sup>2</sup>PAK



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
b	0.70	0.93	0.028	0.037
b1	1.14	1.17	0.044	0.046
b2	1.14	1.17	0.044	0.046
c	0.45	0.60	0.018	0.024
c2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
e	2.40	2.70	0.094	0.106
E	10.0	10.4	0.394	0.409
L	13.1	13.6	0.516	0.535
L1	3.48	3.78	0.137	0.149
L2	1.27	1.40	0.050	0.055

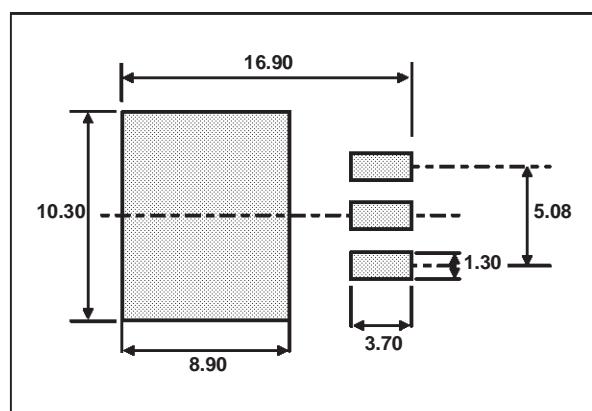
## BYW51/F/G/FP/R-200

### PACKAGE MECHANICAL DATA D<sup>2</sup>PAK



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

### FOOT PRINT (in millimeters) D<sup>2</sup>PAK



**PACKAGE MECHANICAL DATA**  
TO-220FPAB

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.4	4.9	0.173	0.193
B	2.5	2.9	0.098	0.114
D	2.45	2.75	0.096	0.108
E	0.4	0.70	0.016	0.027
F	0.60	1	0.024	0.039
F1	1.15	1.70	0.045	0.067
G	4.95	5.20	0.195	0.204
G1	2.40	2.70	0.094	0.106
H	10	10.7	0.393	0.421
L2	16 Typ.		0.63 Typ.	
L3	28.6	30.6	1.126	1.204
L4	9.8	10.7	0.385	0.421
L6	15.8	16.4	0.621	0.645
L7	9.00	9.90	0.354	0.389
Dia.	2.9	3.50	0.114	0.18

**PACKAGE MECHANICAL DATA**  
ISOWATT220AB (JEDEC compatible)

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
B	2.50	2.70	0.098	0.106
D	2.50	2.75	0.098	0.108
E	0.40	0.70	0.016	0.028
F	0.75	1.00	0.030	0.039
F1	1.15	1.70	0.045	0.067
F2	1.15	1.70	0.045	0.067
G	4.95	5.20	0.195	0.205
G1	2.40	2.70	0.094	0.106
H	10.00	10.40	0.394	0.409
L2	16.00 typ.		0.630 typ.	
L3	28.60	30.60	1.125	1.205
L4	9.80	10.60	0.386	0.417
L6	15.90	16.40	0.626	0.646
L7	9.00	9.30	0.354	0.366
Diam	3.00	3.20	0.118	0.126

<b>Ordering code</b>	<b>Marking</b>	<b>Package</b>	<b>Weight</b>	<b>Base qty</b>	<b>Delivery mode</b>
BYW51-200	BYW51-200	TO220AB	2.2 g.	50	Tube
BYW51F-200	BYW51F-200	ISOWATT220AB	2.08 g.	50	Tube
BYW51G-200	BYW51G-200	D <sup>2</sup> PAK	1.48 g.	50	Tube
BYW51FP-200	BYW51FP-200	TO-220FPAB	2g	50	Tube
BYW51R-200	BYW51R-200	I <sup>2</sup> PAK	1.49 g	50	Tube

- Recommended torque value (TO-220AB): 0.8 N.m.
- Maximum torque value (TO-220AB): 1.0 N.m.
- Recommended torque value (ISOWATT220AB / TO-220FPAB): 0.55 N.m.
- Maximum torque value (ISOWATT220AB / TO-220FPAB): 0.70 N.m.
- Epoxy meets UL94,V0

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